IPC - ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Ir	formatio	on	
upplier Inform	nation													
Company name*			Company unique ID			J	Jnique ID Auth		Response Date*					
nsemi											2024-05-10			
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
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Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requeste	er Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site		ght*	UOM	Unit Type
	CM1624-08DE RLC FILTER W		RLC FILTER W/ES	SD FOR SD	2024-05-10 N		MY1 6.8			mg	Each			
	Process Information		amain al Daga	Allow	STD-020 MSL	Datina	Dool: Droo	aga Dadw T	·	May Time at Peak	Townsoroture	Niversh	er of Reflow Cyc	la c
		Terminal Base Alloy J-STD-CU Alloy 1		S1D-020 MSL	Kaung	Peak Process Body Tempera 260 C		T *				er of Reflow Cyc	ries	
•	n (Sn) - annealed	C	U Alloy	1			1200		ĮC	30	seconds	3		
omments	ima at maak tammanatura	duning sol	domina ia 10 3	20 seconds										
	ime at peak temperature													
r more information	on regarding material co	mposition p	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction that such information is true and correction to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach	0.05	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			Supplier	Epoxy resins	129915-35-1		0.0125	mg
Lead Frame	1.64		Supplier	Silver (Ag)	7440-22-4		0.0049	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0016	mg
			Supplier	Silicon (Si)	7440-21-3		0.0115	mg
			В	Nickel (Ni)	7440-02-0		0.0492	mg
			Supplier	Copper (Cu)	7440-50-8		1.5728	mg
Mold Compound-Black	4.07	mg		Epoxy Phenol Resin	proprietary data		0.4274	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.6427	mg
Plating	0.62	mg	Supplier	Tin (Sn)	7440-31-5		0.62	mg
Wire Bond - Au	0.12	mg	Supplier	Gold (Au)	7440-57-5		0.12	mg